

# MMFTP302K

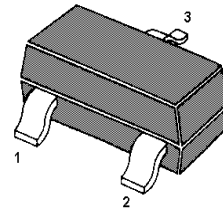
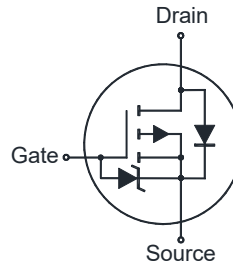
## P-Channel Enhancement Mode MOSFET

### Features

- ESD protected
- Advanced trench cell design
- High speed switch

### Applications

- Portable appliances
- Load switch appliances



1. Gate 2. Source 3. Drain  
SOT-23 Plastic Package

### Absolute Maximum Ratings ( $T_a = 25^\circ\text{C}$ unless otherwise specified)

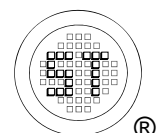
Parameter	Symbol	Value	Unit
Drain-Source Voltage	$-V_{DS}$	25	V
Gate-Source Voltage	$-V_{GS}$	8	V
Drain Current	$-I_D$	0.5	A
Peak Drain Current, Pulsed <sup>1)</sup>	$-I_{DM}$	1	A
Power Dissipation <sup>2)</sup>	$P_D$	0.35	W
Operating Junction and Storage Temperature Range	$T_j, T_{stg}$	- 55 to + 150	$^\circ\text{C}$

### Thermal Characteristics

Parameter	Symbol	Max.	Unit
Thermal Resistance-Junction to Ambient <sup>2)</sup>	$R_{\theta JA}$	357	$^\circ\text{C}/\text{W}$

<sup>1)</sup> Pulse width  $\leq 100 \mu\text{s}$ , duty cycle  $\leq 2\%$ , Repetitive rating, pulse width limited by junction temperature  $T_{J(\text{MAX})} = 150^\circ\text{C}$ .

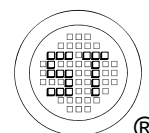
<sup>2)</sup> Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.



# MMFTP302K

Characteristics at  $T_a = 25^\circ\text{C}$  unless otherwise specified

Parameter	Symbol	Min.	Typ.	Max.	Unit
<b>STATIC PARAMETERS</b>					
Drain-Source Breakdown Voltage at $-I_D = 250\ \mu\text{A}$	$-V_{(BR)DSS}$	25	-	-	V
Zero Gate Voltage Drain Current at $-V_{DS} = 20\ \text{V}$	$-I_{DSS}$	-	-	1	$\mu\text{A}$
Gate-Source Leakage At $-V_{GS} = 8\ \text{V}$	$-I_{GSS}$	-	-	10	$\mu\text{A}$
Gate-Source Threshold Voltage at $V_{DS} = V_{GS}$ , $-I_D = 250\ \mu\text{A}$	$-V_{GS(th)}$	0.8	-	2	V
Drain-Source On-State Resistance at $-V_{GS} = 10\ \text{V}$ , $-I_D = 0.5\ \text{A}$ at $-V_{GS} = 4.5\ \text{V}$ , $-I_D = 0.2\ \text{A}$ at $-V_{GS} = 2.7\ \text{V}$ , $-I_D = 0.1\ \text{A}$	$R_{DS(on)}$	-	-	3.6 5.4 11	$\Omega$
<b>DYNAMIC PARAMETERS</b>					
Forward Transconductance at $-V_{DS} = 5\ \text{V}$ , $-I_D = 200\ \text{mA}$	$g_{FS}$	-	0.4	-	S
Input Capacitance at $-V_{DS} = 30\ \text{V}$ , $V_{GS} = 0\ \text{V}$ , $f = 1\ \text{MHz}$	$C_{iss}$	-	42	-	pF
Output Capacitance at $-V_{DS} = 30\ \text{V}$ , $V_{GS} = 0\ \text{V}$ , $f = 1\ \text{MHz}$	$C_{oss}$	-	3.6	-	pF
Reverse Transfer Capacitance at $-V_{DS} = 30\ \text{V}$ , $V_{GS} = 0\ \text{V}$ , $f = 1\ \text{MHz}$	$C_{rss}$	-	1.4	-	pF
Total Gate Charge at $-V_{DS} = 30\ \text{V}$ , $-V_{GS} = 10\ \text{V}$ , $-I_D = 400\ \text{mA}$	$Q_g$	-	1.7	-	nC
Gate-Source Charge at $-V_{DS} = 30\ \text{V}$ , $-V_{GS} = 10\ \text{V}$ , $-I_D = 400\ \text{mA}$	$Q_{gs}$	-	0.5	-	nC
Gate-Drain Charge at $-V_{DS} = 30\ \text{V}$ , $-V_{GS} = 10\ \text{V}$ , $-I_D = 400\ \text{mA}$	$Q_{gd}$	-	0.2	-	nC
Turn-On Rise Time at $-V_{GS} = 10\ \text{V}$ , $-V_{DS} = 30\ \text{V}$ , $-I_D = 400\ \text{mA}$ , $R_G = 3.9\ \Omega$	$t_{d(on)}$	-	6.8	-	ns
Turn-On Rise Time at $-V_{GS} = 10\ \text{V}$ , $-V_{DS} = 30\ \text{V}$ , $-I_D = 400\ \text{mA}$ , $R_G = 3.9\ \Omega$	$t_r$	-	7.5	-	ns
Turn-Off Delay Time at $-V_{GS} = 10\ \text{V}$ , $-V_{DS} = 30\ \text{V}$ , $-I_D = 400\ \text{mA}$ , $R_G = 3.9\ \Omega$	$t_{d(off)}$	-	36	-	ns
Turn-Off Fall Time at $-V_{GS} = 10\ \text{V}$ , $-V_{DS} = 30\ \text{V}$ , $-I_D = 400\ \text{mA}$ , $R_G = 3.9\ \Omega$	$t_f$	-	22	-	ns
<b>Body-Diode PARAMETERS</b>					
Body Diode Voltage at $-I_S = 0.5\ \text{A}$	$-V_{SD}$	-	-	1.3	V
Body-Diode Continuous Current	$-I_S$	-	-	500	mA
Body Diode Reverse Recovery Time at $I_S = 400\ \text{mA}$ , $di/dt = 100\ \text{A} / \mu\text{s}$	$t_{rr}$	-	20	-	nS
Body Diode Reverse Recovery Charge at $I_S = 400\ \text{mA}$ , $di/dt = 100\ \text{A} / \mu\text{s}$	$Q_{rr}$	-	13	-	nC



## Electrical Characteristics Curves

Fig. 1 Typical Output Characteristic

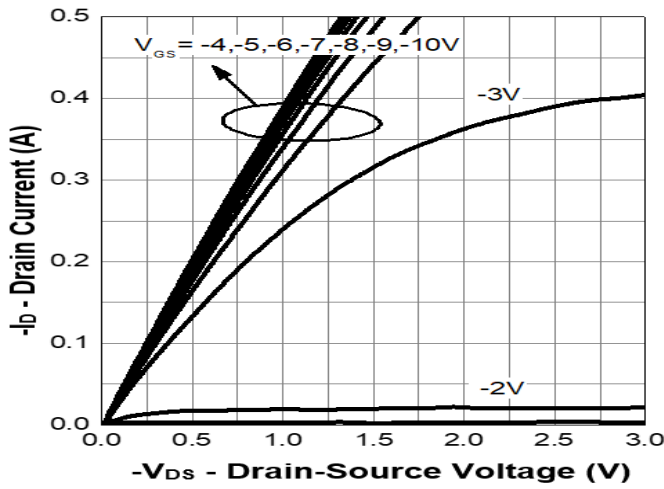


Fig. 2 Gate Threshold Variation vs.  $T_j$

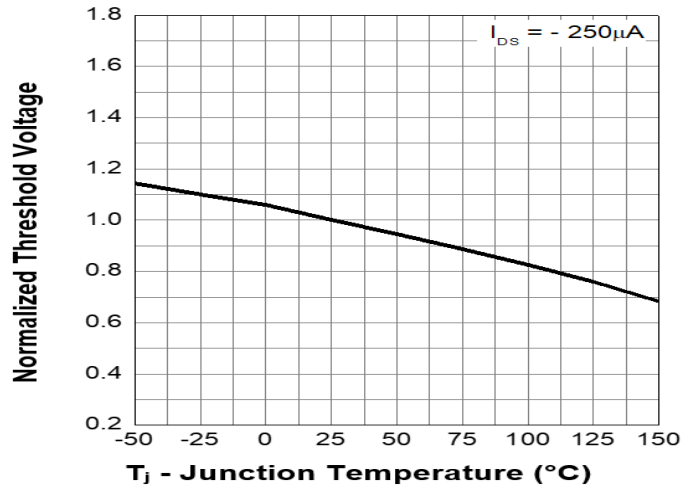


Fig. 3 On-Resistance vs. Gate Voltage

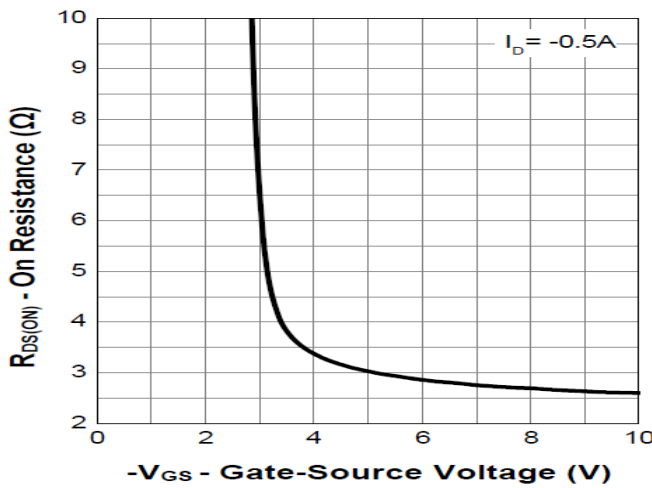


Fig. 4 On-Resistance vs.  $T_j$

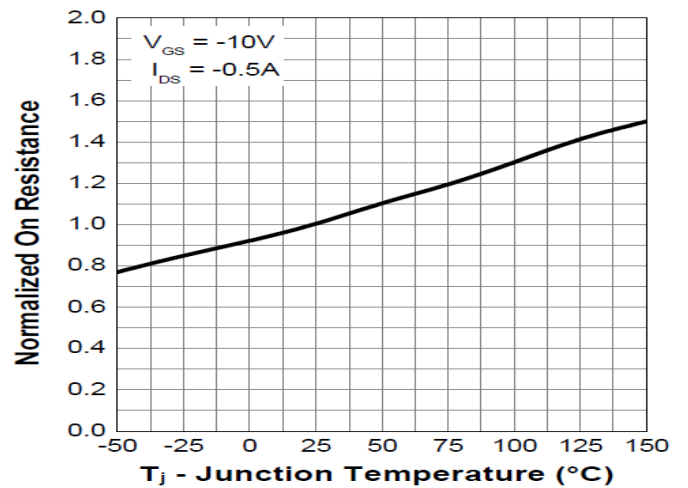


Fig. 5 On-Resistance vs. Drain Current

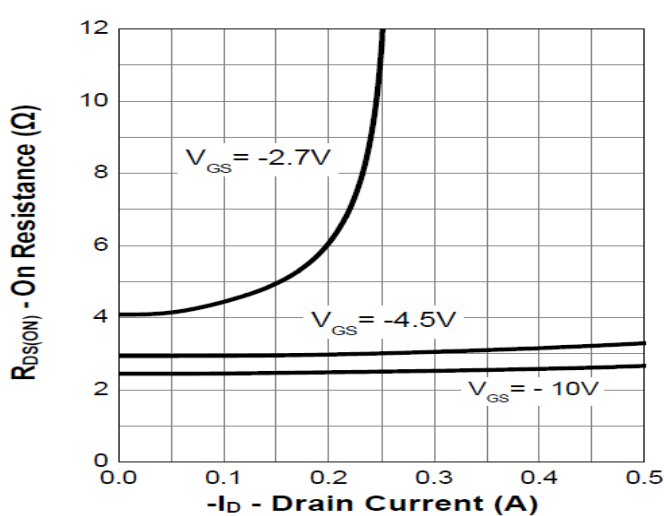
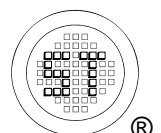
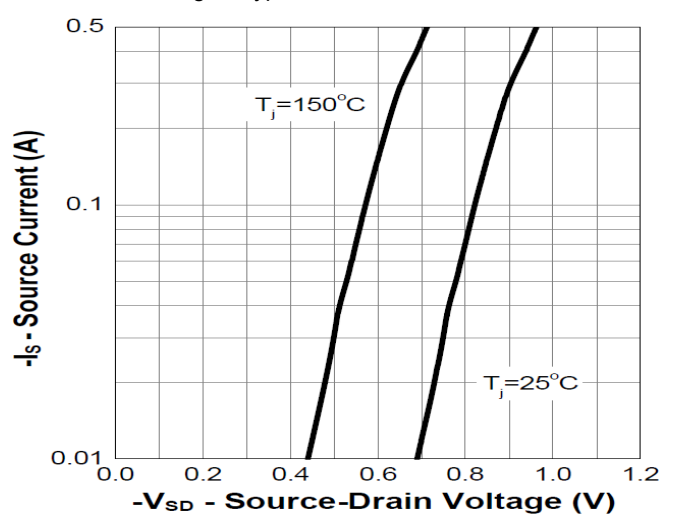


Fig. 6 Typical Forward Characteristic



## Electrical Characteristics Curves

Fig. 7 Typical Junction Capacitance

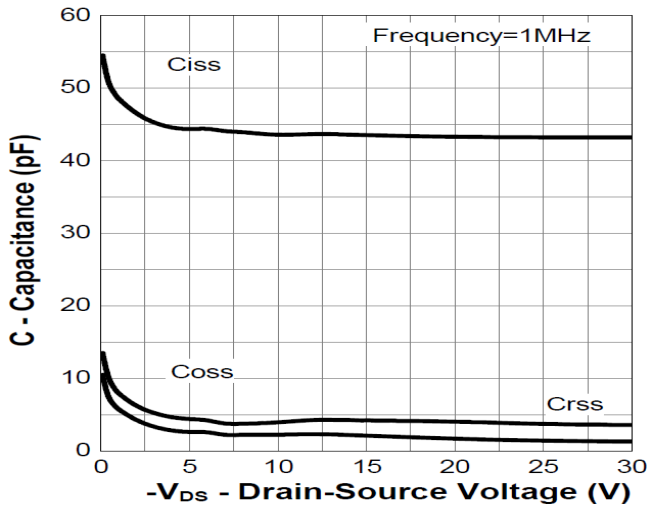
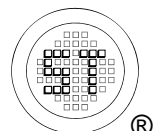
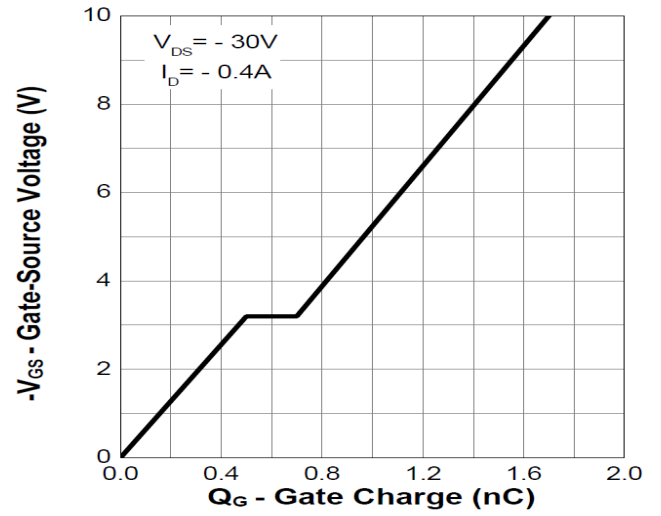


Fig. 8 Gate Charge



## Test Circuits

Fig.1-1 Switching times test circuit

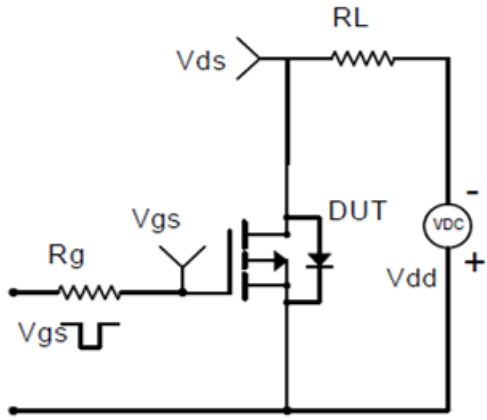


Fig.1-2 Switching Waveform

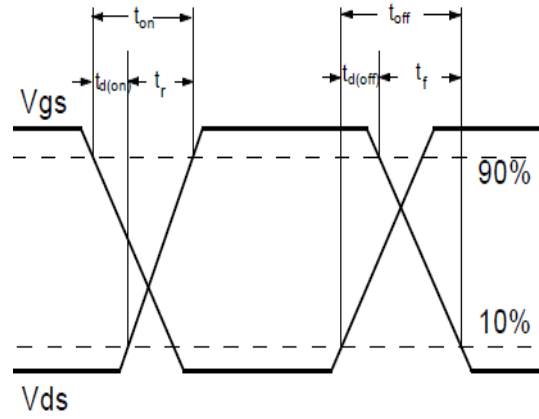


Fig.2-1 Gate charge test circuit

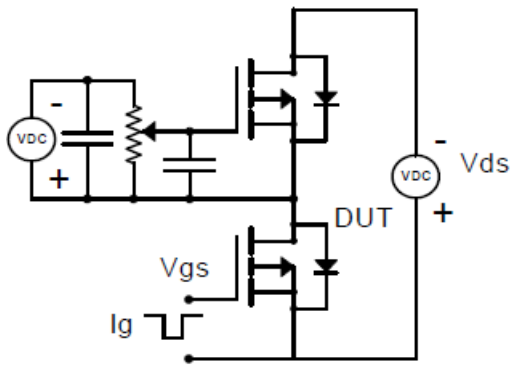
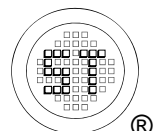
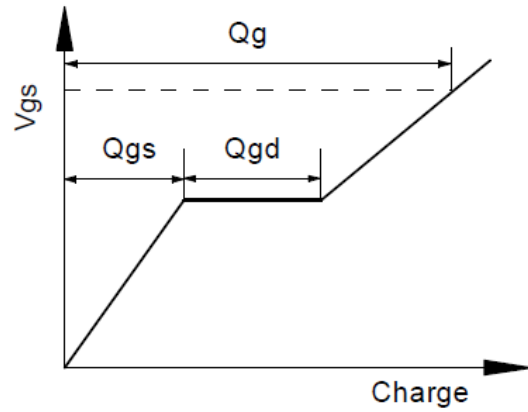


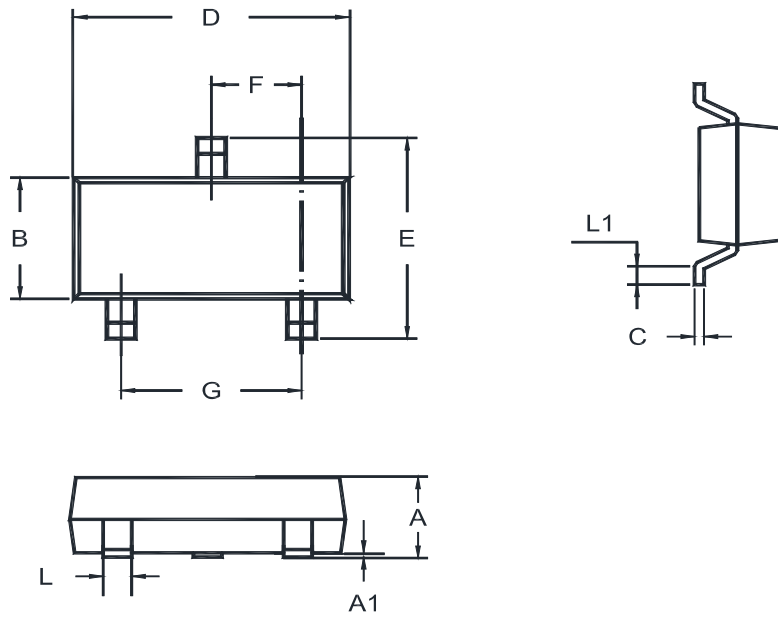
Fig.2-2 Gate charge waveform



# MMFTP302K

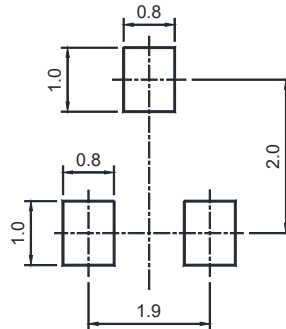
## Package Outline (Dimensions in mm)

SOT-23



Unit	A	A1	B	C	D	E	F	G	L	L1
mm	1.20 0.89	0.100 0.013	1.40 1.20	0.19 0.08	3.04 2.80	2.6 2.2	1.02 0.89	2.04 1.78	0.51 0.37	0.2 MIN

## Recommended Soldering Footprint



## Packing information

Package	Tape Width (mm)	Pitch		Reel Size		Per Reel Packing Quantity
		mm	inch	mm	inch	
SOT-23	8	4 ± 0.1	0.157 ± 0.004	178	7	3,000

## Marking information

- " LP " = Part No.
  - " YM " = Date Code Marking
  - " Y " = Year
  - " M " = Month
- Font type: Arial

